

RELIABILITY REPORT  
FOR

**DS1374, Rev A2**

**Dallas Semiconductor**

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Prepared by:

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**Conclusion:**

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

DS1374, Rev A2

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.

**Device Description:**

A description of this device can be found in the product data sheet. You can find the product data sheet at [http://dbserv.maxim-ic.com/l\\_datasheet3.cfm](http://dbserv.maxim-ic.com/l_datasheet3.cfm).

**Reliability Derating:**

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

$$AfT = \exp((Ea/k) * (1/Tu - 1/Ts)) = tu/ts$$

AfT = Acceleration factor due to Temperature  
tu = Time at use temperature (e.g. 55°C)  
ts = Time at stress temperature (e.g. 125°C)  
k = Boltzmann's Constant (8.617 x 10<sup>-5</sup> eV/°K)  
Tu = Temperature at Use (°K)  
Ts = Temperature at Stress (°K)  
Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

$$AfV = \exp(B * (Vs - Vu))$$

AfV = Acceleration factor due to Voltage  
Vs = Stress Voltage (e.g. 7.0 volts)  
Vu = Maximum Operating Voltage (e.g. 5.5 volts)  
B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

$$Fr = X / (ts * AfV * AfT * N * 2)$$

X = Chi-Sq statistical upper limit  
N = Life test sample size

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

$$\text{MTTF} = 1/\text{Fr}$$

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

**FAILURE RATE:**                      **MTTF (YRS): 5288**                      **FITS: 21.6**

The parameters used to calculate this failure rate are as follows:

**Cf: 60%**                      **Ea: 0.7**                      **B: 0**                      **Tu: 25 °C**                      **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is the device information. This is a description of the device either used as a reliability test vehicle for a process / assembly qualification / monitor or a device used as part of a product qualification / monitor. Following this is the assembly information. This section includes a description of the assembly vehicle used to generate this reliability data for both qualifications and monitors. The next section is the detailed reliability data for each stress found in the qualification / monitor. If there are additional processes or assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that process/assembly. The reliability data section includes the latest data available.

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**Device Information:**

Device: DS1374-18  
Process: D6H-2P2M,HPVt,TCN1 ALOCOS:GOI  
Passivation: Passivation w/Nov TEOS Oxide-Nitride  
Die Size: 58 x 84  
Number of Transistors: 12853  
Interconnect: Aluminum / 1% Silicon / 0.5% Copper  
Gate Oxide Thickness: 150 Å

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**Assembly Information:**

Qualification Vehicle: DS1374-18  
Assembly Site: ATP (Amkor, PI)  
Pin Count: 10  
Package Type: uSOP  
Body Size: 3x0.85  
Mold Compound: Nitto MP8000C  
Lead Frame: Stamped Copper C7025  
Lead Finish: SnPb Plate  
Die Attach: 84-1 LMISR4 Epoxy Silverfilled Ablebond  
Bond Wire / Size: Au / 1.0 mil  
Flammability: UL 94-V0  
Moisture Sensitivity (JEDEC J-STD20A) Level 1  
Date Code Range: 0310 to 0310

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**ELECTRICAL CHARACTERIZATION**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
ESD SENSITIVITY	0310	EOS/ESD S5.1 HBM 500 VOLTS	1 PUL'S	3	0
ESD SENSITIVITY	0310	EOS/ESD S5.1 HBM 1000 VOLTS	1 PUL'S	3	0
ESD SENSITIVITY	0310	EOS/ESD S5.1 HBM 8000 VOLTS	1 PUL'S	3	3
LATCH-UP	0310	JESD78, I-TEST 125C	2 DYS	6	0
LATCH-UP	0310	JESD78, Vsupply TEST 125C	2 DYS	6	0
ESD SENSITIVITY	0310	EOS/ESD S5.1 HBM 2000 VOLTS	1 PUL'S	6	0
ESD SENSITIVITY	0310	EOS/ESD S5.1 HBM 4000 VOLTS	1 PUL'S	6	0
<b>Total:</b>					<b>3</b>

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**MOISTURE SENSITIVITY LEVEL 1**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
EXTERNAL VISUAL	0310	J-STD-020, 6.1a	3 DYS	8	0
ULTRASOUND		J-STD-020	3 DYS	8	0
STORAGE LIFE		125C	24 HRS	8	
MOISTURE SOAK		85 C/85% R.H.	168 HRS	8	
CONVECTION REFLOW		235C	3 PASS	8	0
EXTERNAL VISUAL		J-STD-020, 6.1a	3 DYS	8	0
PRECONDITION U/S		J-STD-020	3 DYS	8	0
<b>Total:</b>					<b>0</b>

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**OPERATING LIFE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
HIGH VOLTAGE LIFE	0310	125C, 6.0 VOLTS	1000 HRS	45	0
<b>Total:</b>					<b>0</b>

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**PACKAGE TESTS**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
SOLDERABILITY	0310	JESD22-B102	6 DYS	3	0
X-RAY	0310	MIL-STD-883-2012 : TOP & SIDE VIEW	3 DYS	6	0
PHYSICAL DIMENSIONS		JESD22-B100	3 DYS	6	0
MARK PERMANENCY		JESD22-B107	3 DYS	6	0
LEAD INTEGRITY		JESD22-B105 TEST CONDITION B	3 DYS	6	0
<b>Total:</b>					<b>0</b>

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**PRECONDITIONING LEVEL 1**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
STORAGE LIFE	0310	125C	24 HRS	308	
MOISTURE SOAK		85 C/85% R.H.	168 HRS	308	
CONVECTION REFLOW		235C	3 PASS	308	0
<b>Total:</b>					<b>0</b>

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**STORAGE LIFE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
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STORAGE LIFE	0310	150C	1000 HRS	77	0
<b>Total:</b>					<b>0</b>

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**TEMPERATURE CYCLE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
TEMP CYCLE	0310	-55C TO 125C	1000 CYS	77	0
<b>Total:</b>					<b>0</b>

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**UNBIASED MOISTURE RESISTANCE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
HAST, NO BIAS	0310	130C, 85% R.H.	96 HRS	73	0
AUTOCLAVE	0310	121C, 2 ATM STEAM, UNBIASED	168 HRS	77	0
<b>Total:</b>					<b>0</b>

**FAILURE RATE:                    MTTF (YRS): 5288                    FITS: 21.6**